

L Number	Hits	Search Text	DB	Time stamp
12	1207	((438/595) or (438/596) or (438/599) or (438/598)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 15:53
13	311	((438/595) or (438/596) or (438/599) or (438/598)).CCLS.) and (wire or wires or wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:26
14	183	rocchegiani	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:28
15	78	circuit adj layout and wiring and gaps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:38
16	26	("4625227"   "4654692"   "4797375"   "4944836"   "4956313"   "5023699"   "5089442"   "5229642"   "5234868"   "5262354"   "5270264"   "5272117"   "5292689"   "5300813"   "5362669"   "5395790"   "5426330"   "5471091"   "5494854"   "5602423"   "5621241"   "5686356"   "6265251"   "6342419"   "6483150"   "6504219").PN.	USPAT	2004/04/01 18:36
17	0	6653717.URPN.	USPAT	2004/04/01 18:37
18	0	6653717.URPN.	USPAT	2004/04/01 18:37
19	7777	((438/689) or (257/E21.243) or (257/E21.273) or (257/E21.58) or (257/E21.581) or (438/584) or (438/595) or (438/645) or (438/646) or (438/656) or (438/692) or (438/758) or (438/789)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:39
20	2409	((438/689) or (257/E21.243) or (257/E21.273) or (257/E21.58) or (257/E21.581) or (438/584) or (438/595) or (438/645) or (438/646) or (438/656) or (438/692) or (438/758) or (438/789)).CCLS.) and (wire or wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:39
21	2530	((438/689) or (257/E21.243) or (257/E21.273) or (257/E21.58) or (257/E21.581) or (438/584) or (438/595) or (438/645) or (438/646) or (438/656) or (438/692) or (438/758) or (438/789)).CCLS.) and (wire\$1 or wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:39
22	460	((438/689) or (257/E21.243) or (257/E21.273) or (257/E21.58) or (257/E21.581) or (438/584) or (438/595) or (438/645) or (438/646) or (438/656) or (438/692) or (438/758) or (438/789)).CCLS.) and (wire\$1 or wiring)) and gap\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 18:39
23	81	((438/689) or (257/E21.243) or (257/E21.273) or (257/E21.58) or (257/E21.581) or (438/584) or (438/595) or (438/645) or (438/646) or (438/656) or (438/692) or (438/758) or (438/789)).CCLS.) and (wire\$1 or wiring)) and gap\$1) and (protrusion\$1 or layout)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 19:32
24	351	(257/210).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 19:40
25	0	wiring and ((bond adj pad) same contact same photoresist same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/01 19:41

26	0	wiring and ((bond adj pad) same hole same photoresist same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:41
27	0	wiring and ((bond adj pad) same hole same photo\$5 same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:41
28	0	wiring and ((bond adj pad) same photo\$5 same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:41
29	0	wiring and ((contact adj pad) same photo\$5 same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:42
30	2	wiring and ((contact adj pad) same photoresist) and (photo same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:43
31	0	wiring and ((contact adj pad) same photo\$5 same mask) and (photo same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:44
32	0	wiring and ((contact adj pad) same photo\$5 same mask) and (photo\$5 same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:44
33	1	wiring and ((contact adj pad) same photo\$5) and (photo\$5 same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:45
34	5	((contact adj pad) same photo\$5) and (photo\$5 same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/01 19:45